

Information Notice

Introduction

- This Information Notice forms part of the European open Tender procedure for Photo-luminescence tool (EPI)-PL mapper, published on 03-04-2026 under TNO reference number WS254751350.
- This Information Notice provides a record of the questions submitted by the Tenderers up to and including the date of publication of this Information Notice with the answers provided by TNO.
- If Tenderers have asked questions of similar nature, all such questions have nevertheless been included in this Information Notice and answered separately. This may result in repetition of information.
- Where a company name was mentioned in a question, it has been replaced by another word or term to anonymize the questions.
- TNO advises you to read the entire Information Notice.
- All information in the Information Notice is classified as Confidential and may only be used for the purpose of submitting a Tender for this procurement.
- The Information Notice will be made available on TenderNed through publication at www.tenderned.nl and added as a document.

The Information Notice serves to provide any additions/changes to the Tender Documents and to communicate announcements from TNO.

Where further clarification of the requirements is provided, this must be taken into account when answering Annex A04 at the time of when compiling the tender. If, for example an alternative is accepted in the Information Notice, Annex A04 will not be revised. The tenderer can answer the question for compliancy with "yes" in both cases (compliance to the original requirement or compliance to the alternative). In case a requirement no longer applies, leave the check box in Annex A04 on "select".

Nr	Subject	Question	Answer
1	Annex A04	Regarding requirement R-1100-020 (Calibration of PL spectra): could the contracting authority please clarify whether the required intensity calibration refers to ensuring consistent and repeatable relative intensity readings, or to correcting the overall system spectral response (i.e. absolute intensity calibration) over the full measurement range?	The intensity of the measured signal should indeed be repeatable relative intensity.
2	Annex A04	Regarding requirement R-1100-055 (Bow measurements): could the contracting authority clarify what output is expected from the system for wafer bow measurements—specifically, whether a numerical value (e.g. maximum warp) is sufficient, or whether a full wafer bow/warp map is required?	A maximum value is sufficient. A full wafer map can be stated as an option in Annex A03 tab 3 P1.
3	Annex A04	Regarding the photoluminescence measurements, could the contracting authority clarify whether a large variation in sample brightness across wafers is expected? This information would be helpful to understand any implications for measurement parameters such as exposure time and throughput, particularly in relation to requirements R-1100-005 and R-2000-005.	We do not expect large variation in sample brightness when there are no problems in the wafer growth. If there are wafer growth issues, we do need the PL mapper to show these "dead zones". The exact spectrum of the "dead zones" is less relevant.
4	Annex A04	Regarding requirement R-1100-005 (Measurement range / excitation conditions), could the contracting authority clarify whether the equipment is intended to characterize InP epitaxial wafers with photoluminescence emission centered around a specific wavelength, or whether variations in wafer structures and epitaxial designs are expected? Additionally, is there interest in supporting multiple excitation wavelengths for the intended characterization use cases?	There will be multiple layers grown with different peak-PL target wavelengths (e.g. 1100nm, 1250nm, 1300nm, 1550nm, etc.). The support of multiple excitation wavelengths, to obtain the best results for different layer stacks, can be stated as an option in Annex A03 tab 3 P1.
5	Pr. Guide7.1	Could the contracting authority please clarify whether any specific ISO certifications are mandatory for the equipment or the supplier, beyond the standards and regulatory requirements explicitly listed in the Program of Requirements?	See Annex A04 R-2000-015, R-2400-005, R-2400-015, R-2500-005

6	Annex A04	Regarding requirement R-3000-005 (Critical Design Review): could the contracting authority clarify whether a fixed or indicative duration is foreseen for the Critical Design Review process itself, or whether its timing is to be agreed between the parties after contract award?	The specifics of the CDR phase will be agreed after contract award.
7	Pr. Guide1.4	With reference to Section 1.4 (Facility and Construction Timeline), could the contracting authority please confirm whether the reference to “mid-February” reflects an indicative earliest delivery window dependent on facility readiness, and that the final delivery schedule for the equipment will be agreed between the parties after contract award and successful completion of the Critical Design Review?	The delivery date will be agreed upon before signing the contract. See article 4 of Annex C02. Circumstances may arise that require this date to be postponed.
8		Could you please provide details on the payment schedule, execution of payments, and applicable payment terms? Additionally, please indicate whether any mandatory payment conditions apply	See Annex A04 R-3000-020.
9	Pr. Guide	Could you please clarify the required warranty period in terms of duration, as well as the specific warranty requirements and expected coverage?	See : "PC Goods TNO 2025", Procurement Guide section 1.
10	Pr. Guide	Could you please confirm whether documentation in English is acceptable, including manuals and related materials, or if all documentation is required to be provided in Dutch?	All documentation shall be in English.
11	Annex A04	Is wafer slot mapping required, including detection of double-slotted and cross-slotted wafers?	This is not required. It can be stated as an option in Annex A03 tab 3 P1.
12	Annex A04	Is a Wafer ID OCR reader required?	This is not required. It can be stated as an option in Annex A03 tab 3 P1.
13	Annex A04	Requirement R-2100-005 (no more than 10 particles > 0.150 µm added per wafer pass) appears to be quite stringent. Could you please clarify the applicable acceptance criteria and evaluation methodology for this requirement?	The PL mapper will be used as an inline measurement tool for product wafers that need further processing in the line, therefore the number of added particles shall be kept to a minimum, hence this stringent requirement. This will be evaluated using a laser scanner such as SurfScan or equivalent.

14	Pr. Guide1.4	Notice from the Contract Authority.	<p>The listing of documentation asked, has been changed . If possible, Tenderer is asked to submit the following information:</p> <p>Drawings and datasheets</p> <ul style="list-style-type: none">• General arrangement drawings;• System layout schematics, including floor plan and required maintenance areas;• Electrical and/or mechanical diagrams, where applicable;• Dimensional data, total weight, weight distribution across the factory floor;• Safety data sheets, if applicable;• Other documentation needed in the opinion of tenderer.
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